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June 2010

FDG1024NZ

Dual N-Channel PowerTrench[®] MOSFET 20 V, 1.2 A, 175 m Ω

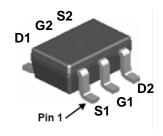
Features

- Max $r_{DS(on)} = 175 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 1.2 \text{ A}$
- Max $r_{DS(on)}$ = 215 m Ω at V_{GS} = 2.5 V, I_D = 1.0 A
- Max $r_{DS(on)} = 270 \text{ m}\Omega$ at $V_{GS} = 1.8 \text{ V}$, $I_D = 0.9 \text{ A}$
- Max $r_{DS(on)}$ = 389 m Ω at V_{GS} = 1.5 V, I_D = 0.8 A
- HBM ESD protection level >2 kV (Note 3)
- Very low level gate drive requirements allowing operation in 1.5 V circuits (V_{GS(th)} < 1 V)
- Very small package outline SC70-6
- RoHS Compliant

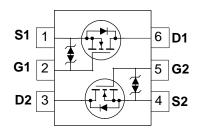


General Description

This dual N-Channel logic level enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for bipolar digital transistors and small signal MOSFETs. Since bias resistors are not required, this dual digital FET can replace several different digital transistors, with different bias resistor values.



SC70-6



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Param	neter		Ratings	Units
V _{DS}	Drain to Source Voltage			20	V
V_{GS}	Gate to Source Voltage			±8	V
1	-Continuous	$T_A = 25$ °C	(Note 1a)	1.2	۸
ID	-Pulsed			6	A
ר	Power Dissipation	T _A = 25°C	(Note 1a)	0.36	W
P_{D}	Power Dissipation	T _A = 25°C	(Note 1b)	0.30	VV
T _J , T _{STG}	Operating and Storage Junction Temper	ature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	350	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	415	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.4N	FDG1024NZ	SC70-6	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	ncteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		14		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 16 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	0.4	8.0	1.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-3		mV/°C
		$V_{GS} = 4.5 \text{ V}, I_D = 1.2 \text{ A}$		160	175	
		$V_{GS} = 2.5 \text{ V}, I_D = 1.0 \text{ A}$		185	215	
r _{DO(})	Static Drain to Source On Resistance	$V_{GS} = 1.8 \text{ V}, I_D = 0.9 \text{ A}$		232	270	mΩ
r _{DS(on)}	Gallo Brain to Godice on Registance	$V_{GS} = 1.5 \text{ V}, I_D = 0.8 \text{ A}$		321	389	11122
		$V_{GS} = 4.5 \text{ V}, I_D = 1.2 \text{ A},$ $T_J = 125 ^{\circ}\text{C}$		220	259	
9 _{FS}	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_{D} = 1.2 \text{ A}$		4		S

Dynamic Characteristics

C _{iss}	Input Capacitance	40.1/. 1/. 0.1/	115	150	pF
C _{oss}	Output Capacitance	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	25	35	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12	20	25	pF
R_g	Gate Resistance		4.6		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		3.7	10	ns
t _r	Rise Time	$V_{DD} = 10 \text{ V}, I_{D} = 1.2 \text{ A},$	1.7	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$	11	19	ns
t _f	Fall Time		1.5	10	ns
Q_{g}	Total Gate Charge	V 45VV 40V	1.8	2.6	nC
Q _{gs}	Gate to Source Charge	V _{GS} = 4.5 V, V _{DD} = 10 V, I _D = 1.2 A	0.3		nC
Q_{gd}	Gate to Drain "Miller" Charge	1D = 1.2 K	0.4		nC

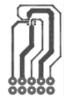
Drain-Source Diode Characteristics

IS	Maximum Continuous Drain-Source Diode Forward Current			0.3	Α
V_{SD}	Source to Drain Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_S = 0.3 \text{ A}$ (Note 2)		0.7	1.2	V
t _{rr}	Reverse Recovery Time	$I_{\rm F} = 1.2 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$	10	20	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 1.2 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$	1.9	10	nC

^{1.} R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0JA} is determined by the user's board design.



a. 350 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 415 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300 µs, Duty cycle < 2.0%.
 3: The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics T_J = 25 °C unless otherwise noted

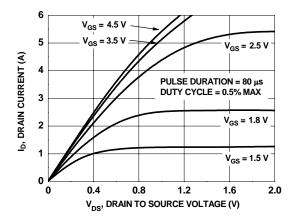


Figure 1. On-Region Characteristics

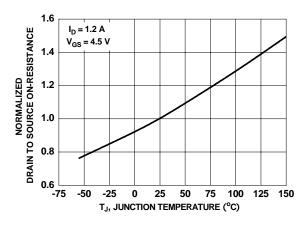


Figure 3. Normalized On-Resistance vs Junction Temperature

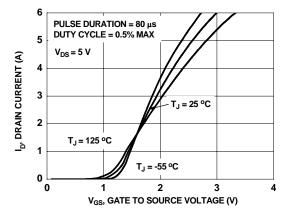


Figure 5. Transfer Characteristics

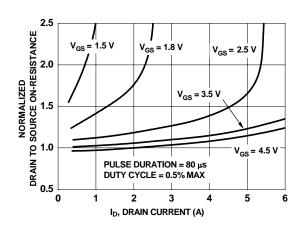


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

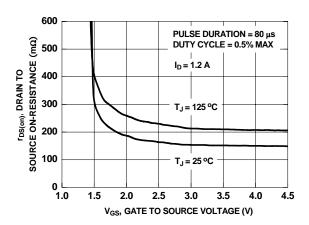


Figure 4. On-Resistance vs Gate to Source Voltage

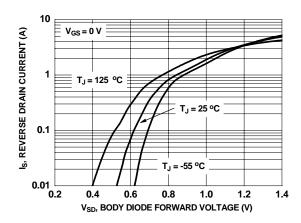


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

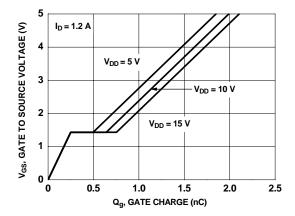


Figure 7. Gate Charge Characteristics

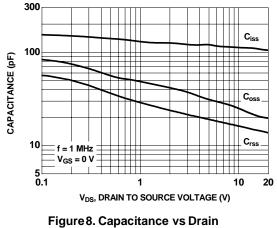


Figure 8. Capacitance vs Drain to Source Voltage

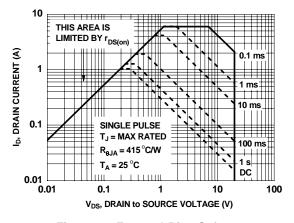


Figure 9. Forward Bias Safe Operating Area

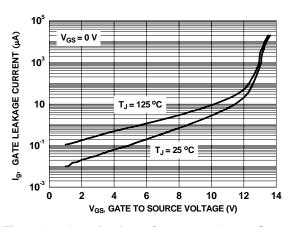


Figure 10. Gate Leakage Current vs Gate to Source Voltage

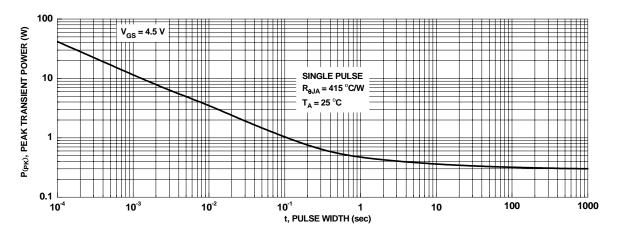


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

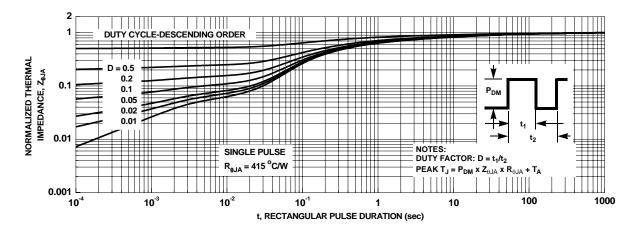
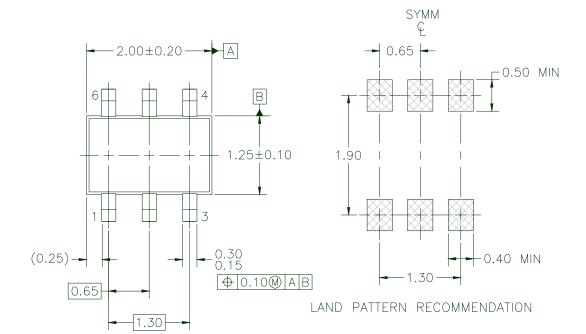
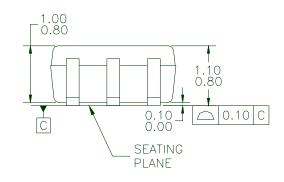
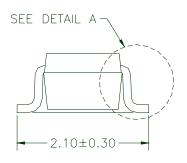


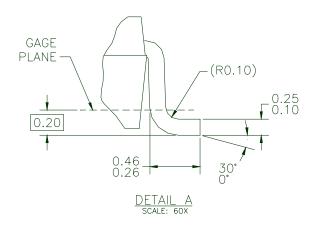
Figure 12. Transient Thermal Response Curve

Dimensional Outline and Pad Layout









NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-88, 1996.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.

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